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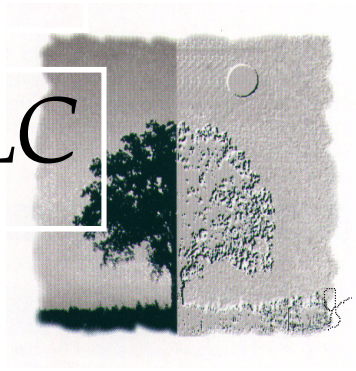
RESIN TECHNOLOGY GROUP, LLC

PRODUCT DATA SHEET



SILVER CONDUCTIVE
Flexible, Silver-Filled Epoxy Adhesive

TIGA 920-H
Flexible Silver Conductive

Description:
TIGA 920-H is a flexible, conductive silver filled epoxy adhesive. It is recommended for bonding, and sealing electronic applications that require high flexibility, conductivity, and mechanical performance. This smooth paste formulation of pure silver and epoxy is free of solvents and extraneous additives. It develops strong, durable, electrically and thermally conductive bonds between many dissimilar materials including metals, ceramics and plastic laminates. TIGA 920-H cures at room temperature and can be used as a flexible "cold solder" for heat sensitive parts. It can also be used in the assembly and repair of flexible circuits, electrical components and electronic shielding.

Typical Physical Properties

Color:	Silver
Specific Gravity:	2.9
Viscosity, cps @ 25°C:	Smooth Paste
Mix Ratio, parts by weight, Resin to Hardener:	100 to 115
Operating Temperature Range:	-60 to 110°C
Hardness, Shore D:	55
Thermal Conductivity, cal-cm/cm^2 sec°C:	37 x 10^{-4}
Reactive solids content, %:	100
Pot Life @ 25°C	3 Hours
Lap Shear Strength (Al/Al	>1000 psi
Lap Shear Strength (Au/Au)	>500 psi
Lap Shear Strength (Kapton®)	>500 psi

Typical Values After Various Cure Schedules:

Bond Line Cure Schedule	Volume Resistivity Ohm-Cm
12-24 Hours @ 25°C	0.005
2 Hours @ 65°C	<0.001
1 Hour @ 110°C	<0.001

Storage
Store below 25°C out of sunlight and in original unopened containers. Refer to packaging specific quote for shelf life information.